

Micro-Abrasive Setup Checklist

SCH Technologies | Vaniman Systems | UK & EU

Purpose: This checklist supports safe, repeatable setup of micro-abrasive blasting systems for controlled conformal coating and Parylene removal.

Scope: Applies to manual and cabinet-based micro-abrasive systems used for PCB rework and selective coating removal.

1. Work Area and Safety

- ☐ Work area is clean, dry and free from loose contamination
- ☐ Local extraction or cabinet filtration is operating correctly
- ☐ Operator PPE available and worn as required
- ☐ Emergency stop and foot pedal operation verified
- ☐ Adequate lighting and magnification available for precision work

2. ESD Control

- ☐ Operator wrist strap connected and verified
- ☐ Cabinet and work surface properly grounded
- ☐ Conductive nozzle fitted if required for electronics work
- ☐ ESD flooring and footwear compliance confirmed where applicable
- ☐ PCB handling follows ESD-safe procedures

3. Air Supply

- ☐ Air supply is clean, dry and oil-free
- ☐ Water traps and filters inspected and drained
- ☐ Regulator operates smoothly and holds stable pressure
- ☐ No air leaks detected in hoses or fittings
- ☐ Air pressure gauge is readable and calibrated if applicable

4. Abrasive Media

- ☐ Correct media type selected for coating and substrate
- ☐ Particle size confirmed for required removal rate and surface protection
- ☐ Media is dry and free from contamination or clumping
- ☐ Media hopper or cartridge filled correctly and sealed
- ☐ Previous media fully purged if a changeover has occurred
- ☐ Media batch and change date recorded if required by quality system

5. Process Parameters

- ☐ Initial air pressure set within target range for coating type
- ☐ Media flow adjusted for stable, consistent delivery
- ☐ Nozzle size appropriate for particle size and access geometry
- ☐ Stand-off distance defined and communicated to operator
- ☐ Angle of attack defined for boundary control and surface protection
- ☐ Test coupon or scrap board prepared for validation

6. Test and Validation

- ☐ Trial removal performed on non-critical area or sample board
- ☐ Removal rate acceptable and controllable
- ☐ No visible solder mask erosion or copper exposure
- ☐ Edge definition acceptable for subsequent recoating
- ☐ No excessive dust generation or media bounce-back
- ☐ Parameters adjusted and re-verified if required

7. Cleaning and Housekeeping

- ☐ Media residue removed from PCB after blasting
- ☐ Work area cleaned of loose abrasive
- ☐ Filters and cabinet inspected after use
- ☐ Waste disposed of according to site procedures
- ☐ Equipment left in safe shutdown condition

8. Documentation and Release

- ☐ Media type and particle size recorded
- ☐ Air pressure and nozzle size recorded
- ☐ Operator name and date recorded
- ☐ Any deviations or issues logged
- ☐ Board released for repair or recoating

Important Note: This checklist provides general technical guidance only. Final process settings, safety controls and acceptance criteria must be validated against product requirements, risk assessments and applicable standards.